



## CALL FOR PAPERS



*The Leading International Symposium on Components, Packaging, and Manufacturing Technology*



## IEEE CPMT Symposium Japan ( Formerly "VLSI Packaging Workshop in Japan" ) Aug. 24-26, 2010

Sanjo Conference Hall, The University of Tokyo, Tokyo, JAPAN

"The VLSI Packaging Workshop in Japan" held every other year since 1992 has become a well-known international workshop for advanced packaging technologies. Due to ever increasing activities and changing demands, the committee has reviewed its mission, cooperated with the members of IEEE CPMT Japan Chapter, refurbished the workshop, and started the new symposium - IEEE CPMT Symposium Japan. It will provide component, packaging, and manufacturing researchers who are extending their activities beyond borders with opportunities to exchange technical knowledge and perspective. The committee strongly encourages you to attend this symposium and participate in the discussion, to understand the technology trends and find the best targets for your technology / business development. Bring your latest research results and share with the participants who are experts from the industry and the grove of Academe, and discuss with them. Anybody contributing to the achievement of a sustainable society through electronics is very welcome at this symposium.

### IEEE CPMT Symposium Japan

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### Topics of Interest include:

- System in a Package, MEMS Packaging
- Advanced Fine Pitch Packaging, 3D Packaging & Chip on Chip
- Nanotechnology, Emerging Technologies
- Micro Bumping Technology, Wafer Level CSP
- Electrical Performance & Thermal Management
- Packaging for Optoelectronics, Packaging for Automobile
- Failure Mechanisms & Reliability Improvement
- Materials for High Speed Application & Wafer Process
- RF Components & Modules / RF Tags
- Integrated Passives / Embedded Components
- Assembly and Packaging Challenges for Cu/Low-k Chips
- Laminated Materials & Processing, Green Material
- Board level reliability System in a Package (SiP)

**You are invited to submit a 500-word abstract to the program chair with the reference of maximum two diagrams. Acceptance will be notified by Mar. 31<sup>st</sup>.**

**Abstract due: Feb 15<sup>th</sup>, 2010**

### Submit to:

Program Chair:  
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